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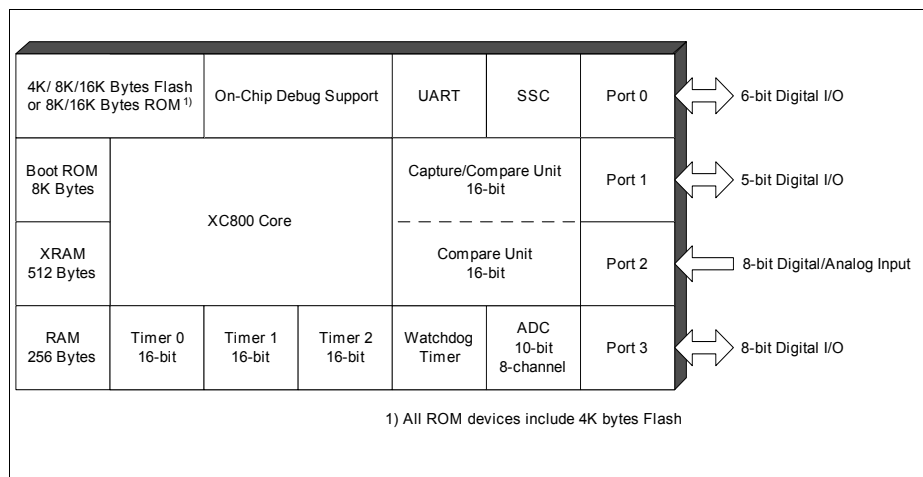
#### Details

Product Status	Last Time Buy
Core Processor	XC800
Core Size	8-Bit
Speed	86MHz
Connectivity	SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	19
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	38-TFSOP (0.173", 4.40mm Width)
Supplier Device Package	PG-TSSOP-38-4
Purchase URL	<a href="https://www.e-xfl.com/product-detail/infineon-technologies/xc8664frabekxuma1">https://www.e-xfl.com/product-detail/infineon-technologies/xc8664frabekxuma1</a>

## 1 Summary of Features

- High-performance XC800 Core
  - compatible with standard 8051 processor
  - two clocks per machine cycle architecture (for memory access without wait state)
  - two data pointers
- On-chip memory
  - 8 Kbytes of Boot ROM
  - 256 bytes of RAM
  - 512 bytes of XRAM
  - 4/8/16 Kbytes of Flash; or  
8/16 Kbytes of ROM, with additional 4 Kbytes of Flash  
(includes memory protection strategy)
- I/O port supply at 3.3 V/5.0 V and core logic supply at 2.5 V (generated by embedded voltage regulator)

(further features are on next page)



**Figure 1 XC866 Functional Units**

Features (continued):

- Reset generation
  - Power-On reset
  - Hardware reset
  - Brownout reset for core logic supply
  - Watchdog timer reset
  - Power-Down Wake-up reset
- On-chip OSC and PLL for clock generation
  - PLL loss-of-lock detection
- Power saving modes
  - slow-down mode
  - idle mode
  - power-down mode with wake-up capability via RXD or EXINT0
  - clock gating control to each peripheral
- Programmable 16-bit Watchdog Timer (WDT)
- Four ports
  - 19 pins as digital I/O
  - 8 pins as digital/analog input
- 8-channel, 10-bit ADC
- Three 16-bit timers
  - Timer 0 and Timer 1 (T0 and T1)
  - Timer 2
- Capture/compare unit for PWM signal generation (CCU6)
- Full-duplex serial interface (UART)
- Synchronous serial channel (SSC)
- On-chip debug support
  - 1 Kbyte of monitor ROM (part of the 8-Kbyte Boot ROM)
  - 64 bytes of monitor RAM
- PG-TSSOP-38 pin package
- Temperature range  $T_A$ :
  - SAF (-40 to 85 °C)
  - SAK (-40 to 125 °C)

**Summary of Features**
**Table 2 Device Summary**

	SAK-XC866*-1FRI 3V	3.3	—	4	—	Industrial
	SAF-XC866*-4FRA 3V	3.3	12	4	—	Automotive
	SAF-XC866*-4FRI 3V	3.3	12	4	—	Industrial
	SAF-XC866*-2FRA 3V	3.3	4	4	—	Automotive
	SAF-XC866*-2FRI 3V	3.3	4	4	—	Industrial
	SAF-XC866*-1FRA 3V	3.3	—	4	—	Automotive
	SAF-XC866*-1FRI 3V	3.3	—	4	—	Industrial
ROM	SAK-XC866*-4RRA	5.0	—	4	16	Automotive
	SAK-XC866*-4RRI	5.0	—	4	16	Industrial
	SAK-XC866*-2RRA	5.0	—	4	8	Automotive
	SAK-XC866*-2RRI	5.0	—	4	8	Industrial
	SAF-XC866*-4RRA	5.0	—	4	16	Automotive
	SAF-XC866*-4RRI	5.0	—	4	16	Industrial
	SAF-XC866*-2RRA	5.0	—	4	8	Automotive
	SAF-XC866*-2RRI	5.0	—	4	8	Industrial
	SAK-XC866*-4RRA 3V	3.3	—	4	16	Automotive
	SAK-XC866*-4RRI 3V	3.3	—	4	16	Industrial
	SAK-XC866*-2RRA 3V	3.3	—	4	8	Automotive
	SAK-XC866*-2RRI 3V	3.3	—	4	8	Industrial
	SAF-XC866*-4RRA 3V	3.3	—	4	16	Automotive
	SAF-XC866*-4RRI 3V	3.3	—	4	16	Industrial
	SAF-XC866*-2RRA 3V	3.3	—	4	8	Automotive
	SAF-XC866*-2RRI 3V	3.3	—	4	8	Industrial

<sup>1)</sup> Industrial is not for Automotive usage

<sup>2)</sup> The flash memory (P-Flash and D-Flash) can be used for code or data.

**Note:** The asterisk (\*) above denotes the device configuration letters from **Table 1**.

**General Device Information**
**Table 3 Pin Definitions and Functions (cont'd)**

Symbol	Pin Number	Type	Reset State	Function
<b>P1</b>		I/O		<b>Port 1</b> Port 1 is a 5-bit bidirectional general purpose I/O port. It can be used as alternate functions for the JTAG, CCU6, UART, and the SSC.
P1.0	27	PU		RXD_0      UART Receive Data Input T2EX        Timer 2 External Trigger Input
P1.1	28	PU		EXINT3     External Interrupt Input 3 TDO_1      JTAG Serial Data Output TXD_0      UART Transmit Data Output/ Clock Output
P1.5	29	PU		CCPOS0_1   CCU6 Hall Input 0 EXINT5      External Interrupt Input 5 EXF2_0      Timer 2 External Flag Output RXD0_0     UART Transmit Data Output
P1.6	9	PU		CCPOS1_1   CCU6 Hall Input 1 T12HR_0     CCU6 Timer 12 Hardware Run Input EXINT6      External Interrupt Input 6
P1.7	10	PU		CCPOS2_1   CCU6 Hall Input 2 T13HR_0     CCU6 Timer 13 Hardware Run Input P1.5 and P1.6 can be used as a software chip select output for the SSC.

## Functional Description

### 3.2.2 Special Function Register

The Special Function Registers (SFRs) occupy direct internal data memory space in the range  $80_H$  to  $FF_H$ . All registers, except the program counter, reside in the SFR area. The SFRs include pointers and registers that provide an interface between the CPU and the on-chip peripherals. As the 128-SFR range is less than the total number of registers required, address extension mechanisms are required to increase the number of addressable SFRs. The address extension mechanisms include:

- Mapping
- Paging

#### 3.2.2.1 Address Extension by Mapping

Address extension is performed at the system level by mapping. The SFR area is extended into two portions: the standard (non-mapped) SFR area and the mapped SFR area. Each portion supports the same address range  $80_H$  to  $FF_H$ , bringing the number of addressable SFRs to 256. The extended address range is not directly controlled by the CPU instruction itself, but is derived from bit RMAP in the system control register SYSCON0 at address  $8F_H$ . To access SFRs in the mapped area, bit RMAP in SFR SYSCON0 must be set. Alternatively, the SFRs in the standard area can be accessed by clearing bit RMAP. The SFR area can be selected as shown in **Figure 8**.

#### SYSCON0

##### System Control Register 0

Reset Value:  $00_H$ 

7	6	5	4	3	2	1	0
		0			1	0	RMAP
		r			rw	r	rw

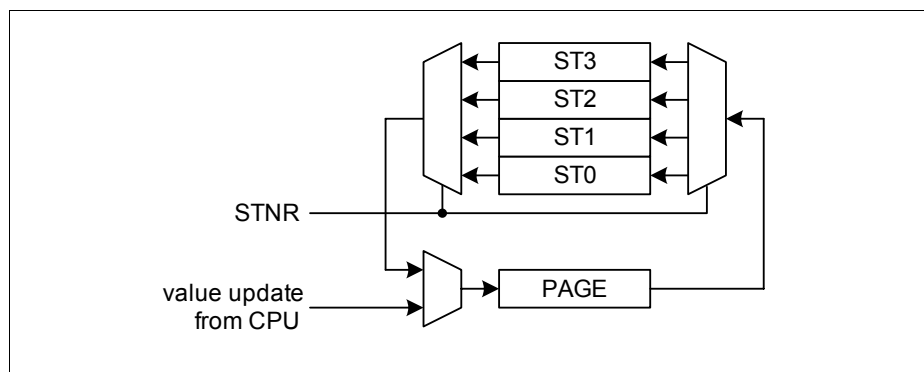
Field	Bits	Type	Description
RMAP	0	rw	<b>Special Function Register Map Control</b> 0 The access to the standard SFR area is enabled. 1 The access to the mapped SFR area is enabled.
1	2	rw	<b>Reserved</b> Returns the last value if read; should be written with 1.
0	1,[7:3]	r	<b>Reserved</b> Returns 0 if read; should be written with 0.

## Functional Description

In order to access a register located in a page different from the actual one, the current page must be left. This is done by reprogramming the bit field PAGE in the page register. Only then can the desired access be performed.

If an interrupt routine is initiated between the page register access and the module register access, and the interrupt needs to access a register located in another page, the current page setting can be saved, the new one programmed and finally, the old page setting restored. This is possible with the storage fields STx (x = 0 - 3) for the save and restore action of the current page setting. By indicating which storage bit field should be used in parallel with the new page value, a single write operation can:

- Save the contents of PAGE in STx before overwriting with the new value (this is done in the beginning of the interrupt routine to save the current page setting and program the new page number); or
- Overwrite the contents of PAGE with the contents of STx, ignoring the value written to the bit positions of PAGE (this is done at the end of the interrupt routine to restore the previous page setting before the interrupt occurred)



**Figure 10 Storage Elements for Paging**

With this mechanism, a certain number of interrupt routines (or other routines) can perform page changes without reading and storing the previously used page information. The use of only write operations makes the system simpler and faster. Consequently, this mechanism significantly improves the performance of short interrupt routines.

The XC866 supports local address extension for:

- Parallel Ports
- Analog-to-Digital Converter (ADC)
- Capture/Compare Unit 6 (CCU6)
- System Control Registers

**Functional Description**
**Table 12 Timer 2 Register Overview (cont'd)**

C1 <sub>H</sub>	<b>T2_T2MOD</b> Timer 2 Mode Register	<b>Reset: 00<sub>H</sub></b>	Bit Field	T2 REGS	T2 RHEN	EDGE SEL	PREN	T2PRE	DCEN
			Type	rw	rw	rw	rw	rw	rw
C2 <sub>H</sub>	<b>T2_RC2L</b> Timer 2 Reload/Capture Register Low	<b>Reset: 00<sub>H</sub></b>	Bit Field	RC2[7:0]					
			Type	rwh					
C3 <sub>H</sub>	<b>T2_RC2H</b> Timer 2 Reload/Capture Register High	<b>Reset: 00<sub>H</sub></b>	Bit Field	RC2[15:8]					
			Type	rwh					
C4 <sub>H</sub>	<b>T2_T2L</b> Timer 2 Register Low	<b>Reset: 00<sub>H</sub></b>	Bit Field	THL2[7:0]					
			Type	rwh					
C5 <sub>H</sub>	<b>T2_T2H</b> Timer 2 Register High	<b>Reset: 00<sub>H</sub></b>	Bit Field	THL2[15:8]					
			Type	rwh					

The CCU6 SFRs can be accessed in the standard memory area (RMAP = 0).

**Table 13 CCU6 Register Overview**

Addr	Register Name	Bit	7	6	5	4	3	2	1	0	
RMAP = 0											
A3 <sub>H</sub>	<b>CCU6_PAGE</b> Page Register for CCU6	<b>Reset: 00<sub>H</sub></b>	Bit Field	OP		STNR		0	PAGE		
			Type	w		w		r	rwh		
RMAP = 0, Page 0											
9A <sub>H</sub>	<b>CCU6_CC63SRL</b> Capture/Compare Shadow Register for Channel CC63 Low	<b>Reset: 00<sub>H</sub></b>	Bit Field	CC63SL							
			Type	rw							
9B <sub>H</sub>	<b>CCU6_CC63SRH</b> Capture/Compare Shadow Register for Channel CC63 High	<b>Reset: 00<sub>H</sub></b>	Bit Field	CC63SH							
			Type	rw							
9C <sub>H</sub>	<b>CCU6_TCTR4L</b> Timer Control Register 4 Low	<b>Reset: 00<sub>H</sub></b>	Bit Field	T12 STD	T12 STR	0		DTRES	T12 RES	T12RS	T12RR
			Type	w	w	r		w	w	w	w
9D <sub>H</sub>	<b>CCU6_TCTR4H</b> Timer Control Register 4 High	<b>Reset: 00<sub>H</sub></b>	Bit Field	T13 STD	T13 STR	0			T13 RES	T13RS	T13RR
			Type	w	w	r			w	w	w
9E <sub>H</sub>	<b>CCU6_MCMOUTSL</b> Multi-Channel Mode Output Shadow Register Low	<b>Reset: 00<sub>H</sub></b>	Bit Field	STRM CM	0		MCMPS				
			Type	w	r	rw					
9F <sub>H</sub>	<b>CCU6_MCMOUTSH</b> Multi-Channel Mode Output Shadow Register High	<b>Reset: 00<sub>H</sub></b>	Bit Field	STRHP	0		CURHS		EXPHS		
			Type	w	r	rw		rw			
A4 <sub>H</sub>	<b>CCU6_ISR</b> Capture/Compare Interrupt Status Register Low	<b>Reset: 00<sub>H</sub></b>	Bit Field	RT12P M	RT12O M	RCC62 F	RCC62 R	RCC61 F	RCC61 R	RCC60 F	RCC60 R
			Type	w	w	w	w	w	w	w	w
A5 <sub>H</sub>	<b>CCU6_ISRH</b> Capture/Compare Interrupt Status Register High	<b>Reset: 00<sub>H</sub></b>	Bit Field	RSTR	RIDLE	RWHE	RCHE	0	RTRPF	RT13 PM	RT13 CM
			Type	w	w	w	w	r	w	w	w
A6 <sub>H</sub>	<b>CCU6_CMPMODIFL</b> Compare State Modification Register Low	<b>Reset: 00<sub>H</sub></b>	Bit Field	0	MCC63 S	0		MCC62 S	MCC61 S	MCC60 S	
			Type	r	w	r		w	w	w	
A7 <sub>H</sub>	<b>CCU6_CMPMODIFH</b> Compare State Modification Register High	<b>Reset: 00<sub>H</sub></b>	Bit Field	0	MCC63 R	0		MCC62 R	MCC61 R	MCC60 R	
			Type	r	w	r		w	w	w	
FA <sub>H</sub>	<b>CCU6_CC60SRL</b> Capture/Compare Shadow Register for Channel CC60 Low	<b>Reset: 00<sub>H</sub></b>	Bit Field	CC60SL							
			Type	rwh							



## Functional Description

**Table 13 CCU6 Register Overview (cont'd)**

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
FF <sub>H</sub>	<b>CCU6_TRPCTRH</b> <b>Reset: 00<sub>H</sub></b> Trap Control Register High	Bit Field	TRPPE N	TRPEN 13	TRPEN					
		Type	rw	rw	rw					
RMAP = 0, Page 3										
9A <sub>H</sub>	<b>CCU6_MCMOUTL</b> <b>Reset: 00<sub>H</sub></b> Multi-Channel Mode Output Register Low	Bit Field	0	R	MCMP					
		Type	r	rh	rh					
9B <sub>H</sub>	<b>CCU6_MCMOUTH</b> <b>Reset: 00<sub>H</sub></b> Multi-Channel Mode Output Register High	Bit Field	0		CURH			EXPH		
		Type	r		rh			rh		
9C <sub>H</sub>	<b>CCU6_ISL</b> <b>Reset: 00<sub>H</sub></b> Capture/Compare Interrupt Status Register Low	Bit Field	T12PM	T12OM	ICC62F R	ICC61F R	ICC61 R	ICC60F R	ICC60 R	
		Type	rh	rh	rh	rh	rh	rh	rh	rh
9D <sub>H</sub>	<b>CCU6_ISH</b> <b>Reset: 00<sub>H</sub></b> Capture/Compare Interrupt Status Register High	Bit Field	STR	IDLE	WHE	CHE	TRPS	TRPF	T13PM	T13CM
		Type	rh	rh	rh	rh	rh	rh	rh	rh
9E <sub>H</sub>	<b>CCU6_PISEL0L</b> <b>Reset: 00<sub>H</sub></b> Port Input Select Register 0 Low	Bit Field	ISTRP		ISCC62		ISCC61		ISCC60	
		Type	rw		rw		rw		rw	
9F <sub>H</sub>	<b>CCU6_PISEL0H</b> <b>Reset: 00<sub>H</sub></b> Port Input Select Register 0 High	Bit Field	IST12HR		ISPOS2		ISPOS1		ISPOS0	
		Type	rw		rw		rw		rw	
A4 <sub>H</sub>	<b>CCU6_PISEL2</b> <b>Reset: 00<sub>H</sub></b> Port Input Select Register 2	Bit Field	0						IST13HR	
		Type	r						rw	
FA <sub>H</sub>	<b>CCU6_T12L</b> <b>Reset: 00<sub>H</sub></b> Timer T12 Counter Register Low	Bit Field	T12CVL							
		Type	rwh							
FB <sub>H</sub>	<b>CCU6_T12H</b> <b>Reset: 00<sub>H</sub></b> Timer T12 Counter Register High	Bit Field	T12CVH							
		Type	rwh							
FC <sub>H</sub>	<b>CCU6_T13L</b> <b>Reset: 00<sub>H</sub></b> Timer T13 Counter Register Low	Bit Field	T13CVL							
		Type	rwh							
FD <sub>H</sub>	<b>CCU6_T13H</b> <b>Reset: 00<sub>H</sub></b> Timer T13 Counter Register High	Bit Field	T13CVH							
		Type	rwh							
FE <sub>H</sub>	<b>CCU6_CMPSTATL</b> <b>Reset: 00<sub>H</sub></b> Compare State Register Low	Bit Field	0	CC63 ST	CCPO S2	CCPO S1	CCPO S0	CC62 ST	CC61 ST	CC60 ST
		Type	r	rh	rh	rh	rh	rh	rh	rh
FF <sub>H</sub>	<b>CCU6_CMPSTATH</b> <b>Reset: 00<sub>H</sub></b> Compare State Register High	Bit Field	T13IM	COUT 63PS	COUT 62PS	CC62 PS	COUT 61PS	CC61 PS	COUT 60PS	CC60 PS
		Type	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh

The SSC SFRs can be accessed in the standard memory area (RMAP = 0).

**Table 14 SSC Register Overview**

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
A9 <sub>H</sub>	<b>SSC_PISEL</b> Reset: 00 <sub>H</sub> Port Input Select Register	Bit Field	0						CIS	SIS
		Type	r						rw	MIS
AA <sub>H</sub>	<b>SSC_CONL</b> Reset: 00 <sub>H</sub> Control Register Low <i>Programming Mode</i>	Bit Field	LB	PO	PH	HB	BM			
		Type	rw	rw	rw	rw	rw			
	<i>Operating Mode</i>	Bit Field	0						BC	
		Type	r						rh	

### 3.7 Reset Control

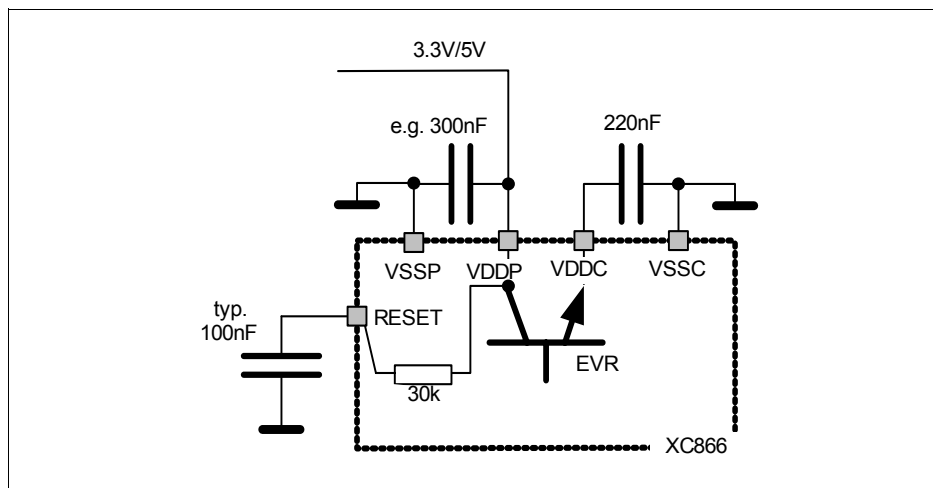
The XC866 has five types of reset: power-on reset, hardware reset, watchdog timer reset, power-down wake-up reset, and brownout reset.

When the XC866 is first powered up, the status of certain pins (see **Table 20**) must be defined to ensure proper start operation of the device. At the end of a reset sequence, the sampled values are latched to select the desired boot option, which cannot be modified until the next power-on reset or hardware reset. This guarantees stable conditions during the normal operation of the device.

In order to power up the system properly, the external reset pin  $\overline{\text{RESET}}$  must be asserted until  $V_{\text{DDC}}$  reaches  $0.9 \cdot V_{\text{DDC}}$ . The delay of external reset can be realized by an external capacitor at  $\overline{\text{RESET}}$  pin. This capacitor value must be selected so that  $V_{\text{RESET}}$  reaches 0.4 V, but not before  $V_{\text{DDC}}$  reaches  $0.9 \cdot V_{\text{DDC}}$ .

A typical application example is shown in **Figure 21**.  $V_{\text{DDP}}$  capacitor value is 300 nF.  $V_{\text{DDC}}$  capacitor value is 220 nF. The capacitor connected to  $\overline{\text{RESET}}$  pin is 100 nF.

Typically, the time taken for  $V_{\text{DDC}}$  to reach  $0.9 \cdot V_{\text{DDC}}$  is less than 50  $\mu\text{s}$  once  $V_{\text{DDP}}$  reaches 2.3V. Hence, based on the condition that 10% to 90%  $V_{\text{DDP}}$  (slew rate) is less than 500  $\mu\text{s}$ , the  $\overline{\text{RESET}}$  pin should be held low for 500  $\mu\text{s}$  typically. See **Figure 22**.



**Figure 21** Reset Circuitry

## Functional Description

The clock system provides three ways to generate the system clock:

### PLL Base Mode

The system clock is derived from the VCO base (free running) frequency clock divided by the K factor.

$$f_{SYS} = f_{VCObase} \times \frac{1}{K}$$

### Prescaler Mode (VCO Bypass Operation)

In VCO bypass operation, the system clock is derived from the oscillator clock, divided by the P and K factors.

$$f_{SYS} = f_{OSC} \times \frac{1}{P \times K}$$

### PLL Mode

The system clock is derived from the oscillator clock, multiplied by the N factor, and divided by the P and K factors. Both VCO bypass and PLL bypass must be inactive for this PLL mode. The PLL mode is used during normal system operation. .

$$f_{SYS} = f_{OSC} \times \frac{N}{P \times K}$$

**Table 3-1** shows the settings of bits OSCDISC and VCOBYP for different clock mode selection.

**Table 3-1 Clock Mode Selection**

OSCDISC	VCOBYP	Clock Working Modes
0	0	PLL Mode
0	1	Prescaler Mode
1	0	PLL Base Mode
1	1	PLL Base Mode

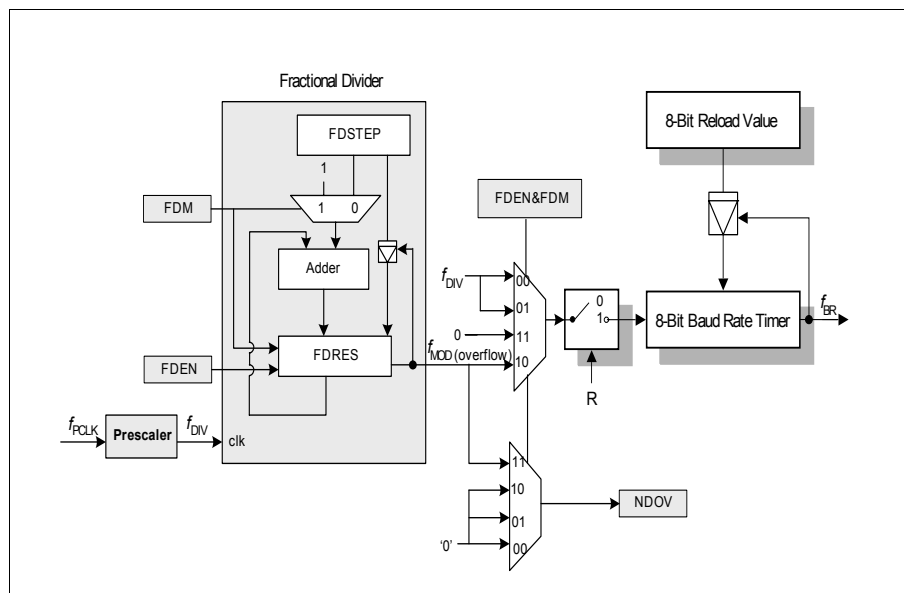
*Note: When oscillator clock is disconnected from PLL, the clock mode is PLL Base mode regardless of the setting of VCOBYP bit.*

### System Frequency Selection

For the XC866, the values of P and K are fixed to “1” and “2”, respectively. In order to obtain the required system frequency,  $f_{sys}$ , the value of N can be selected by bit NDIV for different oscillator inputs. **Table 21** provides examples on how  $f_{sys} = 80$  MHz can be obtained for the different oscillator sources.

### 3.11.1 Baud-Rate Generator

The baud-rate generator is based on a programmable 8-bit reload value, and includes divider stages (i.e., prescaler and fractional divider) for generating a wide range of baud rates based on its input clock  $f_{\text{PCLK}}$ , see **Figure 29**.



**Figure 29 Baud-rate Generator Circuitry**

The baud rate timer is a count-down timer and is clocked by either the output of the fractional divider ( $f_{\text{MOD}}$ ) if the fractional divider is enabled ( $\text{FDCON.FDEN} = 1$ ), or the output of the prescaler ( $f_{\text{DIV}}$ ) if the fractional divider is disabled ( $\text{FDEN} = 0$ ). For baud rate generation, the fractional divider must be configured to fractional divider mode ( $\text{FDCON.FDM} = 0$ ). This allows the baud rate control run bit  $\text{BCON.R}$  to be used to start or stop the baud rate timer. At each timer underflow, the timer is reloaded with the 8-bit reload value in register BG and one clock pulse is generated for the serial channel.

Enabling the fractional divider in normal divider mode ( $\text{FDEN} = 1$  and  $\text{FDM} = 1$ ) stops the baud rate timer and nullifies the effect of bit  $\text{BCON.R}$ . See **Section 3.12**.

The baud rate ( $f_{\text{BR}}$ ) value is dependent on the following parameters:

- Input clock  $f_{\text{PCLK}}$
- Prescaling factor ( $2^{\text{BRPRE}}$ ) defined by bit field BRPRE in register BCON
- Fractional divider ( $\text{STEP}/256$ ) defined by register FDSTEP  
(to be considered only if fractional divider is enabled and operating in fractional divider mode)

## Functional Description

115.2 kHz, using different module clock frequencies. The fractional divider is enabled (fractional divider mode) and the corresponding parameter settings are shown.

**Table 27      Deviation Error for UART with Fractional Divider enabled**

$f_{\text{PCLK}}$	Prescaling Factor ( $2^{\text{BRPRE}}$ )	Reload Value (BR_VALUE + 1)	STEP	Deviation Error
26.67 MHz	1	10 (A <sub>H</sub> )	177 (B1 <sub>H</sub> )	+0.03 %
13.33 MHz	1	7 (7 <sub>H</sub> )	248 (F8 <sub>H</sub> )	+0.11 %
6.67 MHz	1	3 (3 <sub>H</sub> )	212 (D4 <sub>H</sub> )	-0.16 %

### **3.17 Capture/Compare Unit 6**

The Capture/Compare Unit 6 (CCU6) provides two independent timers (T12, T13), which can be used for Pulse Width Modulation (PWM) generation, especially for AC-motor control. The CCU6 also supports special control modes for block commutation and multi-phase machines.

The timer T12 can function in capture and/or compare mode for its three channels. The timer T13 can work in compare mode only.

The multi-channel control unit generates output patterns, which can be modulated by T12 and/or T13. The modulation sources can be selected and combined for the signal modulation.

#### **Timer T12 Features:**

- Three capture/compare channels, each channel can be used either as a capture or as a compare channel
- Supports generation of a three-phase PWM (six outputs, individual signals for highside and lowside switches)
- 16-bit resolution, maximum count frequency = peripheral clock frequency
- Dead-time control for each channel to avoid short-circuits in the power stage
- Concurrent update of the required T12/T13 registers
- Generation of center-aligned and edge-aligned PWM
- Supports single-shot mode
- Supports many interrupt request sources
- Hysteresis-like control mode

#### **Timer T13 Features:**

- One independent compare channel with one output
- 16-bit resolution, maximum count frequency = peripheral clock frequency
- Can be synchronized to T12
- Interrupt generation at period-match and compare-match
- Supports single-shot mode

#### **Additional Features:**

- Implements block commutation for Brushless DC-drives
- Position detection via Hall-sensor pattern
- Automatic rotational speed measurement for block commutation
- Integrated error handling
- Fast emergency stop without CPU load via external signal ( $\overline{\text{CTRAP}}$ )
- Control modes for multi-channel AC-drives
- Output levels can be selected and adapted to the power stage

### 3.19 On-Chip Debug Support

The On-Chip Debug Support (OCDS) provides the basic functionality required for the software development and debugging of XC800-based systems.

The OCDS design is based on these principles:

- use the built-in debug functionality of the XC800 Core
- add a minimum of hardware overhead
- provide support for most of the operations by a Monitor Program
- use standard interfaces to communicate with the Host (a Debugger)

#### Features:

- Set breakpoints on instruction address and within a specified address range
- Set breakpoints on internal RAM address
- Support unlimited software breakpoints in Flash/RAM code region
- Process external breaks
- Step through the program code

The OCDS functional blocks are shown in **Figure 35**. The Monitor Mode Control (MMC) block at the center of OCDS system brings together control signals and supports the overall functionality. The MMC communicates with the XC800 Core, primarily via the Debug Interface, and also receives reset and clock signals. After processing memory address and control signals from the core, the MMC provides proper access to the dedicated extra-memories: a Monitor ROM (holding the code) and a Monitor RAM (for work-data and Monitor-stack). The OCDS system is accessed through the JTAG<sup>1)</sup>, which is an interface dedicated exclusively for testing and debugging activities and is not normally used in an application. The dedicated MBC pin is used for external configuration and debugging control.

*Note: All the debug functionality described here can normally be used only after XC866 has been started in OCDS mode.*

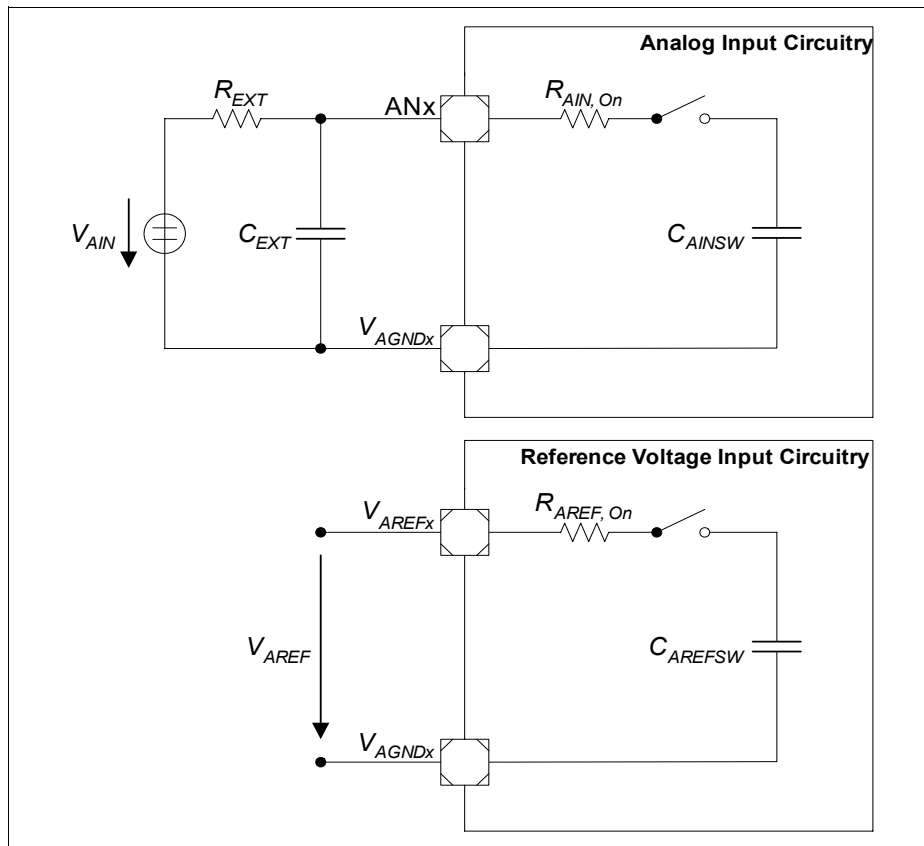
<sup>1)</sup> The pins of the JTAG port can be assigned to either Port 0 (primary) or Ports 1 and 2 (secondary). User must set the JTAG pins (TCK and TDI) as input during connection with the OCDS system.

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**Electrical Parameters**

- <sup>4)</sup> Not subjected to production test, verified by design/characterization. However, for applications with strict low power-down current requirements, it is mandatory that no active voltage source is supplied at any GPIO pin when VDDP is powered off.





**Figure 37 ADC Input Circuits**

#### **4.2.3.1 ADC Conversion Timing**

Conversion time,  $t_C = t_{ADC} \times (1 + r \times (3 + n + STC))$ , where

$r = CTC + 2$  for  $CTC = 00_B, 01_B$  or  $10_B$ ,

$r = 32$  for  $CTC = 11_B$ ,

$CTC$  = Conversion Time Control (GLOBCTR.CTC),

$STC$  = Sample Time Control (INPCR0.STC),

$n = 8$  or  $10$  (for 8-bit and 10-bit conversion respectively),

$t_{ADC} = 1 / f_{ADC}$

## 4.2.4 Power Supply Current

**Table 37 Power Supply Current Parameters (Operating Conditions apply;  
 $V_{DDP} = 5V$  range )**

Parameter	Symbol	Limit Values		Unit	Test Condition Remarks
		typ. <sup>1)</sup>	max. <sup>2)</sup>		
<b><math>V_{DDP}</math> = 5V Range</b>					
Active Mode	$I_{DDP}$	22.6	24.5	mA	<sup>3)</sup>
Idle Mode	$I_{DDP}$	17.2	19.7	mA	XC866-4FR, XC866-2FR <sup>4)</sup>
		12.5	14	mA	XC866-1FR, ROM device <sup>4)</sup>
Active Mode with slow-down enabled	$I_{DDP}$	7.2	8.2	mA	XC866-4FR, XC866-2FR <sup>5)</sup>
		5.6	7.5	mA	XC866-1FR, ROM device <sup>5)</sup>
Idle Mode with slow-down enabled	$I_{DDP}$	7.1	8	mA	XC866-4FR, XC866-2FR <sup>6)</sup>
		5.1	7.2	mA	XC866-1FR, ROM device <sup>6)</sup>

<sup>1)</sup> The typical  $I_{DDP}$  values are periodically measured at  $T_A = +25\text{ °C}$  and  $V_{DDP} = 5.0\text{ V}$ .

<sup>2)</sup> The maximum  $I_{DDP}$  values are measured under worst case conditions ( $T_A = +125\text{ °C}$  and  $V_{DDP} = 5.5\text{ V}$ ).

<sup>3)</sup>  $I_{DDP}$  (active mode) is measured with: CPU clock and input clock to all peripherals running at 26.7 MHz (set by on-chip oscillator of 10 MHz and NDIV in PLL\_CON to 0010<sub>B</sub>), RESET =  $V_{DDP}$ , no load on ports.

<sup>4)</sup>  $I_{DDP}$  (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 26.7 MHz, RESET =  $V_{DDP}$ , no load on ports.

<sup>5)</sup>  $I_{DDP}$  (active mode with slow-down mode) is measured with: CPU clock and input clock to all peripherals running at 833 KHz by setting CLKREL in CMCON to 0101<sub>B</sub>, RESET =  $V_{DDP}$ , no load on ports.

<sup>6)</sup>  $I_{DDP}$  (idle mode with slow-down mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 833 KHz by setting CLKREL in CMCON to 0101<sub>B</sub>, RESET =  $V_{DDP}$ , no load on ports.

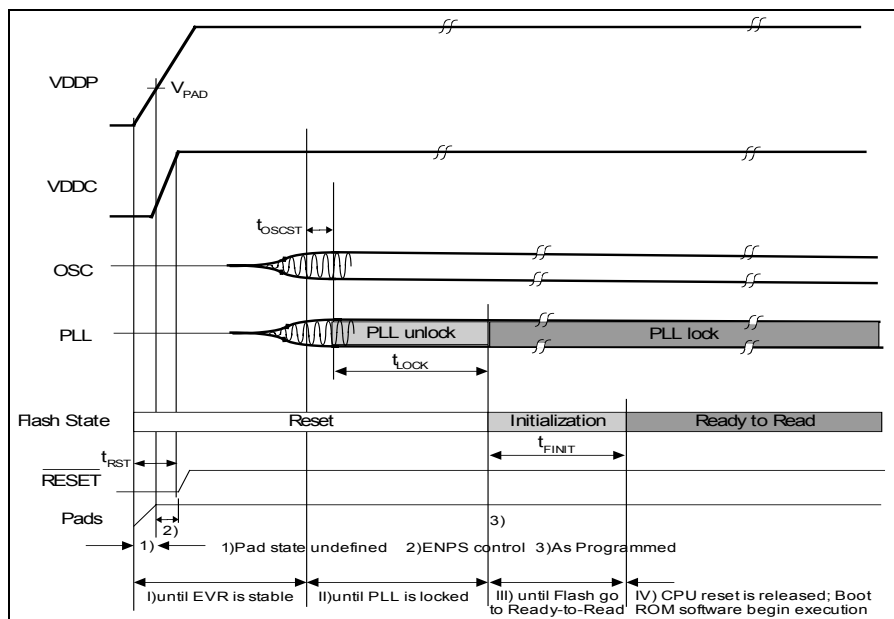
### 4.3.3 Power-on Reset and PLL Timing

**Table 42 Power-On Reset and PLL Timing (Operating Conditions apply)**

Parameter	Symbol	Limit Values			Unit	Test Conditions
		min.	typ.	max.		
Pad operating voltage	$V_{PAD}$ CC	2.3	–	–	V	
On-Chip Oscillator start-up time	$t_{OSCST}$ CC	–	–	500	ns	
Flash initialization time	$t_{FINIT}$ CC	–	160	–	$\mu$ s	
$\overline{RESET}$ hold time <sup>1)</sup>	$t_{RST}$ SR	–	500	–	$\mu$ s	$V_{DDP}$ rise time (10% – 90%) $\leq 500\mu$ s
PLL lock-in in time	$t_{LOCK}$ CC	–	–	200	$\mu$ s	
PLL accumulated jitter	$D_P$	–	–	0.7	ns	<sup>2)</sup>

1)  $\overline{RESET}$  signal has to be active (low) until  $V_{DDC}$  has reached 90% of its maximum value (typ. 2.5V).

2) PLL lock at 80 MHz using a 4 MHz external oscillator. The PLL Divider settings are K = 2, N = 40 and P = 1.

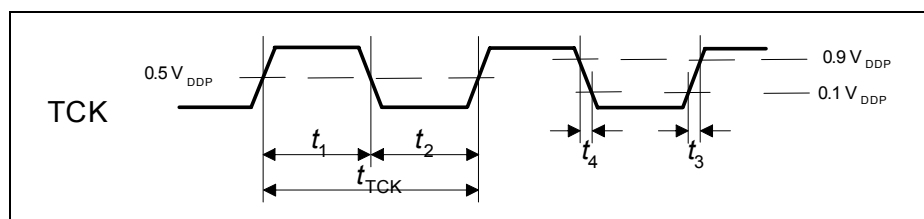


**Figure 42 Power-on Reset Timing**

### 4.3.5 JTAG Timing

**Table 44 TCK Clock Timing (Operating Conditions apply;  $C_L = 50$  pF)**

Parameter	Symbol	Limits		Unit
		min	max	
TCK clock period	$t_{TCK}$ SR	50	–	ns
TCK high time	$t_1$ SR	20	–	ns
TCK low time	$t_2$ SR	20	–	ns
TCK clock rise time	$t_3$ SR	–	4	ns
TCK clock fall time	$t_4$ SR	–	4	ns



**Figure 43 TCK Clock Timing**

## 5 Package and Reliability

### 5.1 Package Parameters (PG-TSSOP-38)

Table 47 provides the thermal characteristics of the package.

**Table 47 Thermal Characteristics of the Package**

Parameter	Symbol		Limit Values		Unit	Notes
			Min.	Max.		
Thermal resistance junction case <sup>1)</sup>	$R_{TJC}$	CC	–	15.7	K/W	–
Thermal resistance junction lead <sup>1)</sup>	$R_{TJL}$	CC	–	39.2	K/W	–

<sup>1)</sup> The thermal resistances between the case and the ambient ( $R_{TCA}$ ), the lead and the ambient ( $R_{TLA}$ ) are to be combined with the thermal resistances between the junction and the case ( $R_{TJC}$ ), the junction and the lead ( $R_{TJL}$ ) given above, in order to calculate the total thermal resistance between the junction and the ambient ( $R_{TJA}$ ). The thermal resistances between the case and the ambient ( $R_{TCA}$ ), the lead and the ambient ( $R_{TLA}$ ) depend on the external system (PCB, case) characteristics, and are under user responsibility.

The junction temperature can be calculated using the following equation:  $T_J = T_A + R_{TJA} \times P_D$ , where the  $R_{TJA}$  is the total thermal resistance between the junction and the ambient. This total junction ambient resistance  $R_{TJA}$  can be obtained from the upper four partial thermal resistances, by

- simply adding only the two thermal resistances (junction lead and lead ambient), or
- by taking all four resistances into account, depending on the precision needed.